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Flame retardant resin composition, used for electronic components - comprises silicone resin and non-silicone resin having aromatic ring, having high flame retardancy, formability and mechanical strength

Patent Assignee: NEC CORP (NIDE)

Inventor: IJI M; SERIZAWA S

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Abstract (Basic): EP 829521 A

A flame retardant resin composition comprises a silicone resin and a non-silicone resin having an aromatic ring, characterised in that the silicone resin has first units of R2SiO1.0 and second units of RSiO1.5 and a molecular weight of not less that 10000, provided that the silicone resin is mixable with the non-silicone resin having the aromatic ring and R is a hydrocarbon group.

USE - Flame retardant resin compositions can be used for electric and electronic components and devices, building materials, automobile parts, daily necessities and the like.

ADVANTAGE - The flame retardant resin composition has a high flame retardancy with addition of a small amount of silicone resin, has a high formability and a high mechanical strength and generates almost no harmful halogen based gases when burning.

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Title Terms: FLAME; RETARD; RESIN; COMPOSITION; ELECTRONIC; COMPONENT; COMPRISE; SILICONE; RESIN; NON; SILICONE; RESIN; AROMATIC; RING; HIGH; FLAME; RETARD; FORMING; MECHANICAL; STRENGTH

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001 018; D18-R; R00470 G1161 G1150 G1149 G1092 D01 D11 D10 D19 D18 D32 D50 D76 D93 F32 F30; P0862 P0839 F41 F44 D01 D63; H0293; H0011-R

002 018; R00817 G0475 G0260 G0022 D01 D12 D10 D26 D51 D53 D58 D83 F12; R00806 G0828 G0817 D01 D02 D12 D10 D51 D54 D56 D58 D84; R00708

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- *003* 018; R00708 G0102 G0022 D01 D02 D12 D10 D19 D18 D31 D51 D53 D58 D76 D88; H0000; H0011-R; P1741 ; P1752
- *004* 018; D18-R; P0464-R D01 D22 D42 F47
- *005* 018; D18-R; P0226 P0282-R D01 D18 F30
- *006* 018; B9999 B4239; Q9999 Q7330-R; Q9999 Q6826-R; Q9999 Q9234 Q9212; Q9999 Q9289 Q9212; B9999 B4091-R B3838 B3747; K9745-R; N9999 N6439; K9892; ND04; K9449; N9999 N5970-R; N9999 N6155; N9999 N6780-R N6655
- *007* 018; A999 A419; A999 A497 A486; A999 A555 A486; A999 A000-R; A999 A602 A566; A999 A102 A077; A999 A624-R A566; A999 A340-R; A999 A715 A691; A999 A237
- *008* 018; A999 A544 A486; K9869 K9847 K9790

<02>

- *001* 018; D01 D11 D10 D19 D18 D31 D32 D76 D50 D82 D86 D87 F81 F86; P1445-R F81 Si 4A; M9999 M2153-R; M9999 M2777
- *002* 018; B9999 B5094 B4977 B4740; B9999 B4239; Q9999 Q7330-R; Q9999 Q6826-R; Q9999 Q9234 Q9212; Q9999 Q9289 Q9212; B9999 B4091-R B3838 B3747; K9745-R; N9999 N6439; K9892; ND04; K9449; N9999 N5970-R; N9999 N6155; N9999 N6780-R N6655
- *003* 018; Si 4A; H0157